Professor Ah-Young Park

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Prof. Ah-Young Park received her B.S. and M.S. degrees from KAIST in 2009 and 2011, respectively, and her Ph.D. degree from the State University of New York at Binghamton in 2017. She joined Corning Incorporated at the Sullivan Park Science and Technology Center in New York in 2015, where she focused on finite element structural analysis for Corning's new glass technologies. From May 2019, she worked as a senior researcher at the Korea Institute of Machinery and Materials (KIMM) for 6 years. She is currently an Assistant Professor in the Department of Materials Science and Engineering at the University of Seoul, leading the Advanced Packaging Laboratory. Her current research interests include interfacial reliability in hybrid bonding and warpage control in 3D packaging.